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Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		Forehope Electronic (Ningbo) Co.,Ltd.							
Product Name:		TLSR8355F128ET24							
Weight(Unit):		30.9290 mg						Date:	2023/10/17
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	1.0468	Silicon	7440-21-3	1.0468	100.00%	3.38%	1000000
Die2	GD Die	SMIC BJ	0.1699	Silicon	7440-21-3	0.1699	100.00%	0.55%	1000000
Lead Frame	A194	新恒汇	23.1258	Copper	7440-50-8	22.4320	97.00%	55.23%	970000
				Silver	7440-22-4	0.0809	0.35%	0.26%	3500
				Iron	7439-89-6	0.5550	2.40%	1.79%	24000
				Zinc	7440-66-6	0.0347	0.15%	0.11%	1500
				Phosphorus	7723-14-0	0.0231	0.10%	0.07%	1000
DAF	ATB-F100E	Henkel	0.0153	Silicon dioxide	7631-86-9	0.0084	55.0%	0.01%	550000
				Modified epoxy resin	Trade Secret	0.0038	25.0%	0.01%	250000
				Poly[oxy[(2-oxiranyl)-1,2-cyclohexanediyl]], a-hydro-w-hydroxy-, ether with 2-ethyl-	244772-00-7	0.0012	8.0%	0.00%	80000
				2-(hydroxymethyl)-1,3-propanediol (3:1)					
				Phenol-formaldehyde polymer	9003-35-4	0.0012	8.0%	0.00%	80000
				Bisphenol-A-(epichlorhydrin)	25068-38-6	0.0006	4.0%	0.00%	40000
Epoxy	503CuM	理均	0.1957	Diethylene glycol monoethyl ether acetate	112-15-2	0.0090	4.6000%	0.17%	46000
				Silver flake	7440-22-4	0.1526	78.0000%	0.49%	780000
				Acylate resin	Proprietary	0.0157	8.0000%	0.05%	80000
				Epoxy resin	Proprietary	0.0176	9.0000%	0.06%	90000
				Peroxide	Proprietary	0.0008	0.4000%	0.00%	4000
Wire	R2SS 0.8mil	乐金	0.1498	Copper	7440-50-8	0.1446	96.5500%	0.36%	965500
				Palladium	7440-05-3	0.0046	3.1000%	0.02%	31000
				Gold	7440-57-5	0.0005	0.3500%	0.00%	3500
Mold Compound	G630	Sumitomo	5.4243	Epoxy Resin A	Trade Secret	0.1085	2.00%	43.61%	20000
				Epoxy Resin B	Trade Secret	0.1085	2.00%	0.35%	20000
				Phenol Resin	Trade Secret	0.3797	7.00%	1.23%	70000
				Silica(Amorphous)A	60676-86-0	4.3394	80.00%	14.03%	800000
				Silica(Amorphous)B	7631-86-9	0.3255	6.00%	1.05%	60000
				Metal Hydroxide	Trade Secret	0.1356	2.50%	0.44%	25000
				Carbon Black	1333-86-4	0.0271	0.50%	0.09%	5000
Plating	TIN	YunNan Tin	0.8014	Tin	7440-31-5	0.8013	99.99%	2.17%	999900
				other	Trade secret	0.0001	0.01%	0.00%	100
Total			30.9290			30.9290	100%	1000000	